

**Amendments to the Specification:**

Please replace the paragraph beginning at page 2, line 19, with the following redlined paragraph:

Figure 1 shows a cross-section of a device formed on two wafers before the latter are bonded together using the process according to the invention;

Figure 2 shows the device of Figure 1 after bonding;

Figure 3 is a perspective and sectional view of the device of Figure 31;

Figure 3A is a top plan view of the device of Figure 3;

Figure 4 shows a cross-section of a connection structure according to the invention during self-alignment of two parts;

Figure 5 shows the cross-section of Figure 4, after bonding the two parts;

Figure 6 shows a cross-section of an optical device formed in two wafers bonded using the process according to the invention; and

Figure 7 is a top plan view of one of the two wafers of Figure 6.